

Title (en)

COPPER-CONTAINING POLYESTER MOULDING COMPOUND, AND PRODUCTION AND USE THEREOF

Title (de)

KUPFERENTHALTENDE FORMMASSE AUS POLYESTER IHRE HERSTELLUNG UND VERWENDUNG

Title (fr)

MATIÈRE À MOULER CONTENANT DU CUIVRE ET CONSTITUÉE DE POLYESTER, PRODUCTION ET UTILISATION DE LADITE MATIÈRE

Publication

**EP 2125942 A1 20091202 (DE)**

Application

**EP 08701084 A 20080111**

Priority

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- DE 102007003648 A 20070118

Abstract (en)

[origin: WO2008086982A1] The invention relates to a moulding compound containing: i) between 0.001 and 10 wt. % - in relation to the total weight of the constituents (i) to (iii) - of copper or a copper alloy predominantly containing copper; ii) between 0.001 and 99.999 wt. % of at least one polyester based on aromatic dicarboxylic acids and an aliphatic or aromatic dihydroxy compound; and/or iii) between 0 and 99.999 wt. % of a polyester consisting of: A) a (cyclo)aliphatic dicarboxylic acid or the ester-forming derivatives thereof and B) a diol constituent consisting of a (cyclo)alkane diol; and iv) between 0 and 300 wt. % - in relation to the weight of the constituents (i) to (iii) - of standard auxiliary agents and additives.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

See references of WO 2008086982A1

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